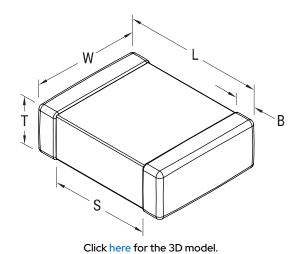


## C1812X122MATAC7210

SMD Comm X8G HT150C Flex, Ceramic, 1,200 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Dimensions		Specifications	
Chip Size	1812	Capacitance	1,200 pF
L	4.5mm +/-0.4mm	Measurement Condition	1 kHz 1.0Vrms
W	3.2mm +/-0.3mm	Tolerance	20%
т	1mm +/-0.10mm	Voltage DC	250 VDC
S	2.3mm MIN	Dielectric Withstanding Voltage	625 VDC
В	0.7mm +/-0.35mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1kH
Packaging	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity	4000	Discipation Factor	

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	Dielectric Withstanding Voltage	625 VDC
	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
Таре	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.